

IN THE SPECIFICATION:

Please replace the paragraph beginning at page 2, line 15, with:

One possible alternative is to provide permanent connections between the bonding pads inside the area array to corresponding peripheral bonding pads for wafer-level testing. However, this approach is usually appropriate only for digital signal pads, since for analog signal pads the connecting wires may add unacceptable amounts of parasitic resistance and capacitance, thereby degrading analog signal performance during normal operation of the subsequently-packaged integrated circuit.